

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

1-14 Canceled

15. (Original) A method for making an optical device package comprising:
- a) providing at least one substrate having an upper surface, a distal end and a proximal end, the substrate having a recess and a linear groove extending between the distal end of the substrate and the recess;
  - b) mounting an optical fiber in said groove, the optical fiber having an optical axis, said optical fiber having a top surface and being mounted in the linear groove of the substrate;
  - c) forming at least one electrical lead on the substrate, the electrical lead extending at least from the recess to the proximal end of the substrate; and,
  - d) fixedly mounting a frame having an opening to the upper surface of the substrate the frame having a top surface and a flat bottom surface, the frame being mounted such that the opening is positioned over at least a portion of the recess in the substrate and the bottom surface of the frame is at or above the level of the top surface of the optical fiber.
16. (Original) The method of claim 15 further including the steps of: mounting an optical semiconductor component to the substrate such that the optical semiconductor component is at least operatively aligned with the optical axis of the optical fiber; and fixedly mounting a lid to the upper surface of the frame.
17. (Original) The method of claim 15 wherein the substrate is single crystal silicon and the upper surface is in the (100) crystallographic plane.

18. (Original) The method of claim 17 wherein the step of providing a substrate comprises forming the recess and linear groove by masking the silicon substrate and etching the silicon substrate in the (111) crystallographic planes.
19. (Original) The method of claim 16 wherein the step of mounting the semiconductor device is performed after the step of fixedly mounting the frame to the upper surface of the substrate.
20. (Original) The method of claim 15 wherein the step of fixedly mounting the frame to the substrate is performed by bonding the frame to the substrate with a material selected from the group consisting of solder metal, solder glass frit, BCB and epoxy resin.
21. (Original) The method of claim 15 wherein the step of providing a substrate comprises providing a silicon wafer, masking and etching the wafer to form a plurality of recesses and grooves, and dividing the wafer into individual substrates, each substrate having at least one recess and at least one groove.
22. (Original) The method of claim 21 wherein the step of dividing the wafer into individual substrates comprises cutting the wafer with a dicing saw.